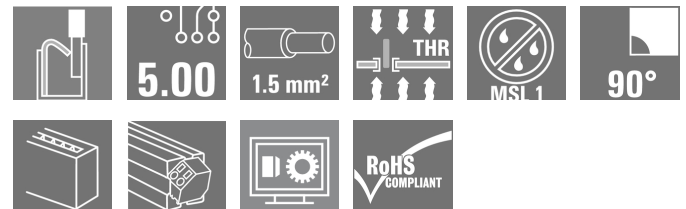


OMNIMATE Signal - series LSF LSF-SMT 5.00/06/90 3.5SN BK TU

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 16
D-32758 Detmold
Germany
Fon: +49 5231 1429-0
Fax: +49 5231 14292083
www.weidmueller.com



PCB terminal for fully automatic assembly in reflow soldering (SMT), with Push In conductor connection system. Conductor inserted and slider operated in same direction (TOP). Packed in box or as tape on reel. Pin lengths optimised at 1.5 mm or 3.5 mm.

- 0.20 - 1.5 mm² (IEC) / 24 - 16 AWG (UL)
- 500 V (IEC) / 300 V (UL)
- 17.5 A (IEC) / 12 A (UL)

General ordering data

| | |
|--------------|---|
| Type | LSF-SMT 5.00/06/90 3.5SN BK TU |
| Order No. | 1824780000 |
| Version | PCB terminal, 5.00 mm, No. of poles: 6, 90°, Solder pin length (l): 3.5 mm, Black, PUSH IN, Clamping range, rated connection, max.: 1.5 mm ² , Tube; Rs = 10 ⁹ - 10 ¹² Ω |
| GTIN (EAN) | 4032248327331 |
| Qty. | 18 pc(s). |
| Product data | IEC: 500 V / 17.5 A / 0.2 - 1.5 mm ² UL: 300 V / 12 A / AWG 24 - AWG 16 |
| Packaging | Tube; Rs = 10 ⁹ - 10 ¹² Ω |

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Technical data
Dimensions and weights

Net weight 5.722 g

System parameters

| | | | |
|--|------------------------------|--|------------------------|
| Product family | OMNIMATE Signal - series LSF | Wire connection method | PUSH IN |
| Mounting onto the PCB | THT/THR solder connection | Conductor outlet direction | 90° |
| Pitch in mm (P) | 5 mm | Pitch in inches (P) | 0.197 inch |
| No. of poles | 6 | Fitted by customer | No |
| Solder pin length (l) | 3.5 mm | Solder pin length tolerance | 0 / -0.3 mm |
| Solder pin dimensions | 0.35 x 0.8 mm | Solder pin dimensions = d tolerance | 0 / -0.1 mm |
| Solder eyelet hole diameter (D) | 1.1 mm | Solder eyelet hole diameter tolerance (D)+ | 0, 1 mm |
| Number of solder pins per pole | 2 | Stripping length | 8 mm |
| L1 in mm | 25 mm | L1 in inches | 0.985 inch |
| Touch-safe protection acc. to DIN VDE 0470 | IP 20 | Touch-safe protection acc. to DIN VDE 57 106 | Safe from finger touch |
| Volume resistance | 1.60 mΩ | | |

Material data

| | | | |
|---------------------------------------|--------------|---------------------------------------|---------------------|
| Insulating material | LCP GF | Colour | Black |
| Colour chart (similar) | RAL 9011 | Insulating material group | IIIa |
| CTI | ≥ 175 | Insulation resistance | ≥ 10 ⁸ Ω |
| Moisture Level (MSL) | 1 | UL 94 flammability rating | V-0 |
| Contact material | Copper alloy | Layer structure of solder connection | 4-6 μm Sn matt |
| Storage temperature, min. | -25 °C | Storage temperature, max. | 55 °C |
| Max. relative humidity during storage | 80 % | Operating temperature, min. | -50 °C |
| Operating temperature, max. | 120 °C | Temperature range, installation, min. | -30 °C |
| Temperature range, installation, max. | 120 °C | | |

Conductors suitable for connection

| | | | |
|---|----------------------|---|----------------------|
| Clamping range, rated connection, min. | 0.13 mm ² | Clamping range, rated connection, max. | 1.5 mm ² |
| Wire connection cross section AWG, min. | AWG 24 | Wire connection cross section AWG, max. | AWG 16 |
| Solid, min. H05(07) V-U | 0.2 mm ² | Solid, max. H05(07) V-U | 1.5 mm ² |
| Flexible, min. H05(07) V-K | 0.2 mm ² | Flexible, max. H05(07) V-K | 1.5 mm ² |
| w. plastic collar ferrule, DIN 46228 pt 4, min. | 0.25 mm ² | w. plastic collar ferrule, DIN 46228 pt 4, max. | 0.75 mm ² |
| w. wire end ferrule, DIN 46228 pt 1, min. | 0.25 mm ² | w. wire end ferrule, DIN 46228 pt 1, max. | 1.5 mm ² |

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Technical data


Rated data acc. to IEC

| | | | |
|---|------------------------|---|------------------|
| tested acc. to standard | IEC 60664-1, IEC 61984 | Rated current, min. no. of poles (Ta = 20°C) | 17.5 A |
| Rated current, max. no. of poles (Ta = 20°C) | 17.5 A | Rated current, min. no. of poles (Ta = 40°C) | 17.5 A |
| Rated current, max. no. of poles (Ta = 40°C) | 15 A | Rated voltage for surge voltage class / pollution degree II/2 | 500 V |
| Rated voltage for surge voltage class / pollution degree III/2 | 320 V | Rated voltage for surge voltage class / pollution degree III/3 | 250 V |
| Rated impulse voltage for surge voltage class/ pollution degree II/2 | 4 kV | Rated impulse voltage for surge voltage class/ pollution degree III/2 | 4 kV |
| Rated impulse voltage for surge voltage class/ contamination degree III/3 | 4 kV | Short-time withstand current resistance | 3 x 1s with 80 A |

Rated data acc. to CSA

| | | | |
|-------------------------------|---|-------------------------------|----------------|
| Institute (CSA) |  | Certificate No. (CSA) | 200039-1664286 |
| Rated voltage (Use group B) | 300 V | Rated voltage (use group D) | 300 V |
| Rated current (use group B) | 10 A | Rated current (use group D) | 10 A |
| Wire cross-section, AWG, min. | AWG 24 | Wire cross-section, AWG, max. | AWG 16 |
| Reference to approval values | Specifications are maximum values, details - see approval certificate. | | |

Rated data acc. to UL 1059

| | | | |
|-------------------------------|---|-------------------------------|--------|
| Institute (cURus) |  | Certificate No. (cURus) | E60693 |
| Rated voltage (use group B) | 300 V | Rated voltage (use group D) | 300 V |
| Rated current (use group B) | 12 A | Rated current (use group D) | 10 A |
| Wire cross-section, AWG, min. | AWG 24 | Wire cross-section, AWG, max. | AWG 16 |
| Reference to approval values | Specifications are maximum values, details - see approval certificate. | | |

Classifications

| | | | |
|------------|-------------|------------|-------------|
| ETIM 3.0 | EC001284 | ETIM 4.0 | EC002643 |
| ETIM 5.0 | EC002643 | ETIM 6.0 | EC002643 |
| UNSPSC | 30-21-18-01 | eClass 6.2 | 27-26-11-01 |
| eClass 7.1 | 27-44-04-01 | eClass 8.1 | 27-44-04-01 |
| eClass 9.0 | 27-44-04-01 | eClass 9.1 | 27-44-04-01 |

Data sheet

**OMNIMATE Signal - series LSF
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Technical data

Notes

- | | |
|-------|--|
| Notes | <ul style="list-style-type: none"> • Additional push button colours on request • Operating force of slider max. 40 N • Rated current related to rated cross-section & min. No. of poles. • Wire end ferrule with plastic collar to DIN 46228/4 • Wire end ferrule without plastic collar to DIN 46228/1 • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • Crimping shape "A" for wire end ferrules with PZ 6/5 crimping tool are recommended for the largest cable sizes. |
|-------|--|

| | |
|----------------|--|
| IPC conformity | The products are developed, manufactured and delivered according to the internationally recognised IPC-A-610 standard, category "permissible". More extensive demands on the products can be evaluated on request. |
|----------------|--|

Approvals

Approvals



| | |
|------|---------|
| ROHS | Conform |
|------|---------|

Downloads

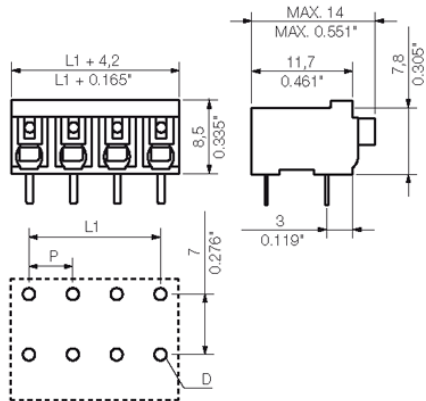
| | |
|---|--|
| Approval/Certificate/Document of Conformity | Declaration of the Manufacturer |
| Brochure/Catalogue | FL DRIVES EN FL ANALO.SIGN.CONV. EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN CAT 2 PORTFOLIOGUIDE EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL INVERTER EN FL_BASE_STATION EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN |
| Engineering Data | EPLAN_WSCAD |
| Engineering Data | LSF-SMT.zip |
| SMT white paper | Download Whitepaper |

OMNIMATE Signal - series LSF
LSF-SMT 5.00/06/90 3.5SN BK TU

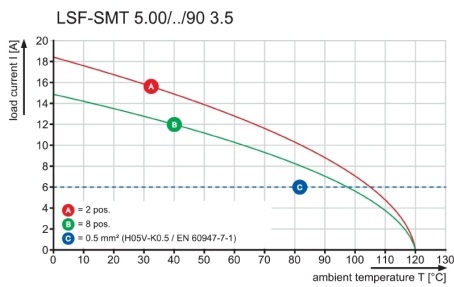
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Drawings

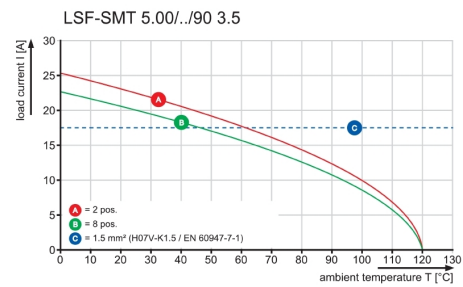
Dimensional drawing



Graph



Graph



Recommended wave soldering profiles

Weidmüller Interface GmbH & Co. KG
 Klängenbergstraße 16
 D-32758 Detmold
 Germany
 Fon: +49 5231 14-0
 Fax: +49 5231 14-292083
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG
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 Germany
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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.